## **DSA8004**

### Silicon PNP epitaxial planar type

For low frequency output amplification DSA7004 in MT-2 through hole type package

#### ■ Features

- $\bullet$  Low collector-emitter saturation voltage  $V_{\text{CE(sat)}}$
- Contributes to miniaturization of sets, mount area reduction
- Eco-friendly Halogen-free package

#### ■ Packaging

Radial type: 2000 pcs / carton

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	-60	V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	-50	V
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	-5	V
Collector current	$I_{C}$	-2	A
Peak collector current	I <sub>CP</sub>	-3	A
Collector power dissipation *	P <sub>C</sub>	1	W
Junction temperature	T <sub>j</sub>	150	°C
Storage temperature	T <sub>stg</sub>	-55 to +150	°C

Note) \*: Printed circuit board: Copper foil area of  $1~\rm cm^2$  or more, and the board thickness of  $1.7~\rm mm$  for the collector portion

### ■ Package

Code

MT-2-A2-B

- Pin Name
  - 1. Emitter
  - 2. Collector
  - 3. Base
- Marking Symbol: 4B

#### ■ Electrical Characteristics $T_a = 25$ °C±3°C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	$V_{CBO}$	$I_{\rm C} = -10 \mu\text{A}, I_{\rm E} = 0$	-60			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_{\rm C} = -1 \text{ mA}, I_{\rm B} = 0$	-50			V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = -10 \mu\text{A}, I_C = 0$	-5			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = -20 \text{ V}, I_{E} = 0$			-0.1	μΑ
Forward current transfer ratio *1	h <sub>FE1</sub> *2	$V_{CE} = -2 \text{ V}, I_{C} = -200 \text{ mA}$	120		340	
	h <sub>FE2</sub>	$V_{CE} = -2 \text{ V}, I_C = -1 \text{ A}$	60			
Collector-emitter saturation voltage *1	V <sub>CE(sat)</sub>	$I_C = -1 \text{ A}, I_B = -50 \text{ mA}$		-0.2	-0.3	V
Base-emitter saturation voltage *1	V <sub>BE(sat)</sub>	$I_{\rm C} = -1 \text{ A}, I_{\rm B} = -50 \text{ mA}$		- 0.9	-1.2	V
Transition frequency	$f_T$	$V_{CE} = -10 \text{ V}, I_{C} = -50 \text{ mA}$		130		MHz
Collector output capacitance (Common base, input open circuited)	C <sub>ob</sub>	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		33	60	pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

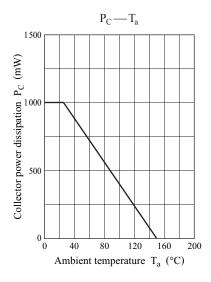
<sup>\*2:</sup> Rank classification

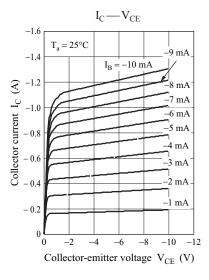
Code	R	S	0
Rank	R	S	No-rank
$h_{\mathrm{FE1}}$	120 to 240	170 to 340	120 to 340
Marking Symbol	4BR	4BS	4B

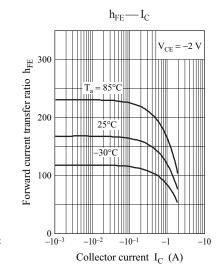
Product of no-rank is not classified and have no marking symbol for rank.

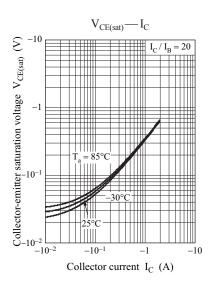
<sup>2. \*1:</sup> Pulse measurement

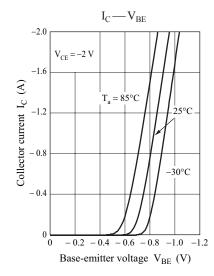
DSA8004 Panasonic

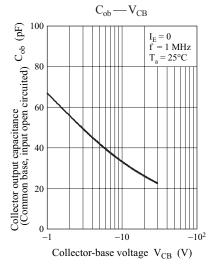


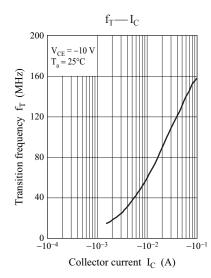








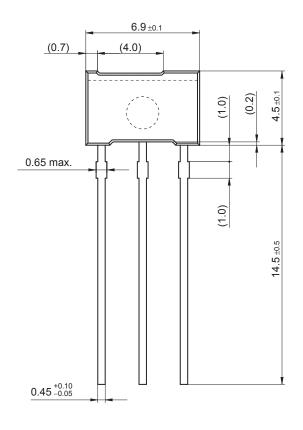


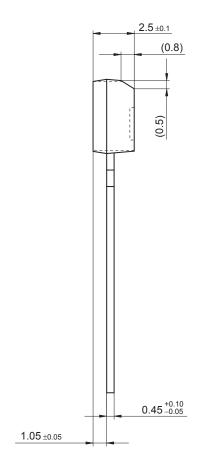


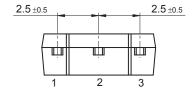
2 Ver. BED

Panasonic DSA8004

MT-2-A2-B Unit: mm







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